SIRIUS 1 LF Di

SOLDER PASTE
NO-CLEAN
"LEAD FREE"

Created : 06/05/2002 Updated : 09/09/2021 Index : 10

DESCRIPTION

SIRIUS 1 LF Di no-clean dispensing grade solder paste has been developed in MBO laboratories. It is designed to offer a high level of activity by leaving low residues, clear and non-corrosive. This product, suitable for dispensing applications meets the international requirements of the electronics industry.

- **ROL0 classification (J-STD-004)**
- Halide free.
- **RoHS compliant**.
- High activity.
- Low and neutral residues.
- Extended tack-life (>24 hours).
- Excellent slump resistance.

SIRIUS 1 LF Di no-clean dispensing grade solder paste is manufactured in compliance with the international standards.

AVAILABLE ALLOYS

Alloy	*Alloy number ISO 9453 (2014)*	*Melting Point (°C)*	*Metal content (%)*	*Viscosity (Pas)*
Sn96.5Ag3.5	703	221	85 - 86	300 - 500
Sn96.5Ag3Cu0.5	711	217/220	85 - 86	300 - 500
Sn95.5Ag3.8Cu0.7	713	217	85 - 86	300 - 500
Sn99Ag0.3Cu0.7	501	217/227	85 - 86	300 - 500
Sn98.5Ag0.8Cu0.7	715	217/224	85 - 86	300 - 500
Sn99CuSP	401	227	85 - 86	300 - 500
Sn97Cu3	402	227/310	85 - 86	300 - 500
Sn43Bi57	301	139	85 - 86	300 - 500
Sn42Bi57Ag1	NA	139	85 - 86	300 - 500
Other : consult us				

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TECHNICAL DATA

Category	Standard	Results
Activity Level (classification)	IPC J-STD-004	**ROL0**
Halide Content	IPC J-STD-004	**Halide free (by titration)**
Copper Mirror	IPC-TM-650 (2.3.32) /J-STD-004	**Pass** (no evidence of corrosion)
Silver Chromate	IPC-TM-650 (2.3.33)	**Pass**
Surface Insulation Resistance Test (SIR)	GR 78 Core Section 13, 13.1.3.2	**Pass, $1x10^{12}$ ohms**
Electromigration Resistance Testing	GR-78-Core Section 13.1.4	**Pass, >$1x10^{10}$ ohms**
Visual aspect of residues	IPC-HDBK-005	**Clear**
Viscosity	Malcom spiral viscometer (J-STD-005)	**370 Pa.s (SAC 305)**
Solder ball test	IPC J-STD-005	**Acceptable**

DISPENSING

SIRIUS 1 LF Di has been designed for most types of solder paste dispensing machines equipped with needles down to 0.41 mm (using 25-45µm). Finer dispensing needles require lower size solder powder.

Ambient conditions
18-22°C and 35% to 70% RH. Minimize exposure of solder paste direct to air flow.

Cleaning Nozzles and Tools
Use MBO Easy Purge 400 conditioning fluid.

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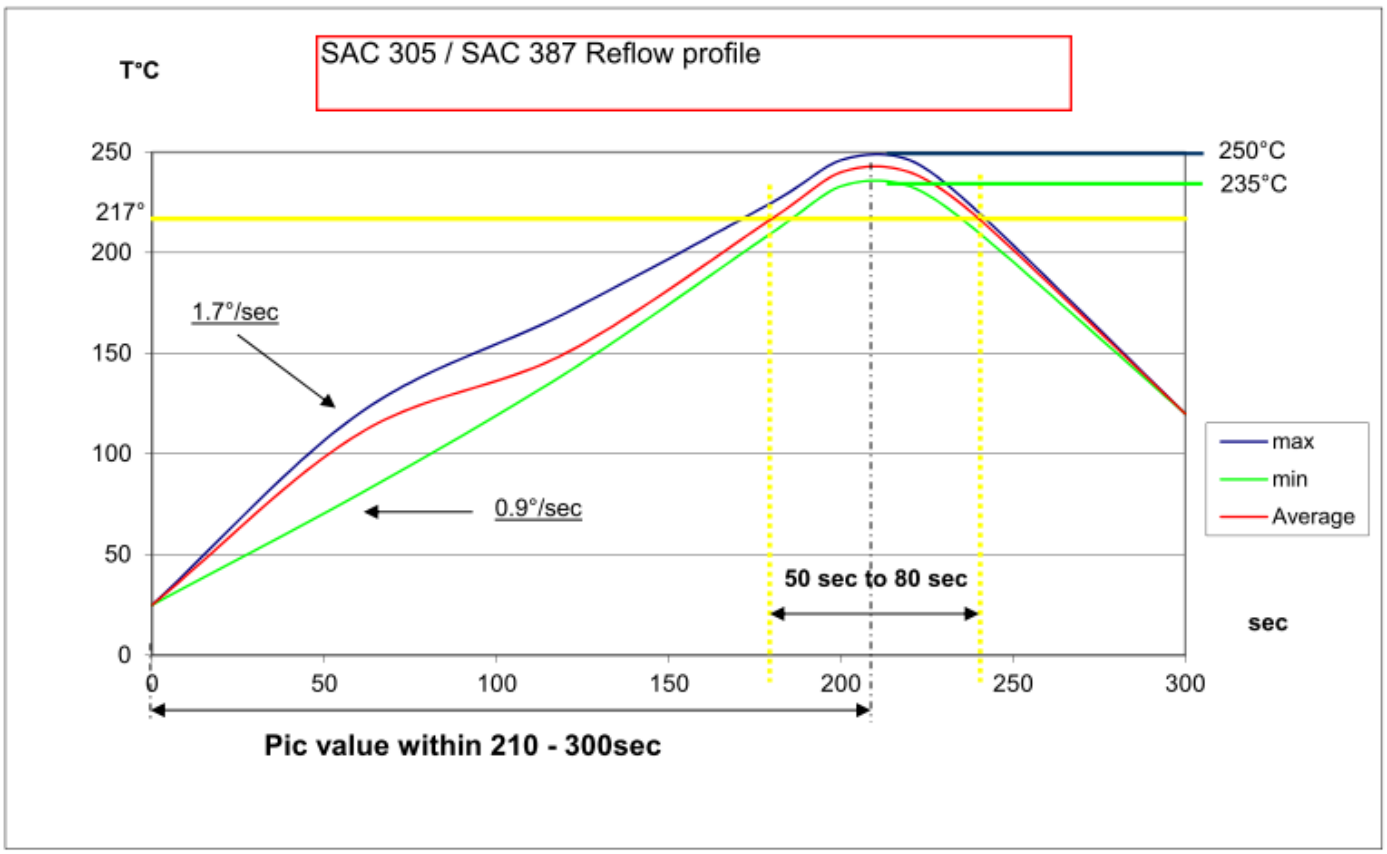
REFLOW

Heating Methods
Convection, infrared, vapour phase, hot plate, hot bar, laser and others. Aerobic or inerted.

Heating Profile
See suggested reflow profile for specific alloy.

Cleaning Equipment
Spray, immersion, vapour degreaser or scrubber.



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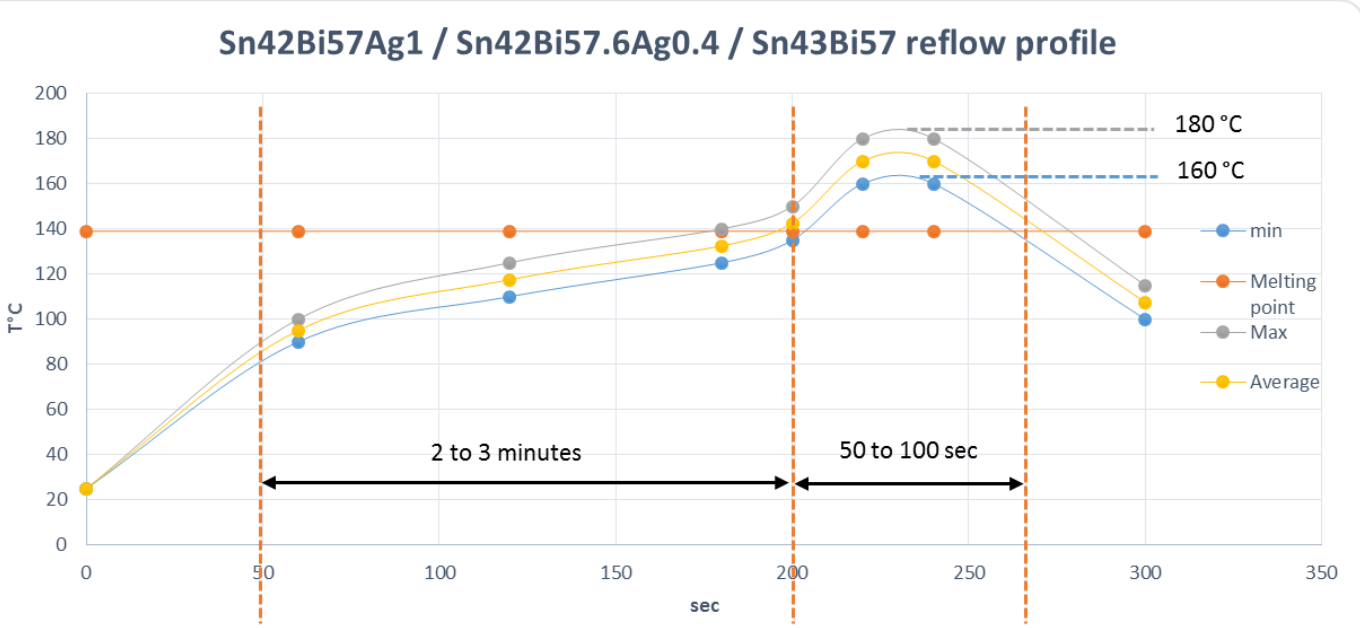

STORAGE AND PACKAGING

Packaging: syringes and cartridges of 5cc, 10cc, 30cc and 50cc - others on request.

Storage: in original container between 5 and 10°C for up to 6 months. Wait until the syringe has reached the ambient temperature before using to avoid water condensation on the surface of the paste. Once opened if the syringe is emptied in 2-3 days, do not return to the fridge. Before using the syringe , it could be stored at ambient conditions (around 20 °C) within one week.

Additional information:
Our manufacturing processes have been subjected to FMECA analysis (equivalent of AMDEC in France).

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